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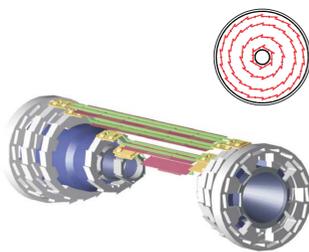
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ABSTRACT
A major upgrade of the KEKB factory (Tsukuba, Japan) is foreseen until 2013, aiming at a luminosity of up to $8 \times 10^{35} \text{ cm}^{-2}\text{s}^{-1}$, which is about 40 times the present value. Accordingly, a similar increase is expected for trigger rate and occupancy of the Silicon Vertex Detector (SVD). The current readout system has a shaping time of 800 ns, no multi-event memory and thus requires a trigger within this period. As it already operates at its limit, it obviously has to be replaced for the upgrade.

We developed a readout system using the APV25 chip with a shorter shaping time of 50 ns, 40 MHz readout and an integrated 192 cell deep analog pipeline. By taking six consecutive samples of the shaper output and processing these data with FPGAs on a VME module we can determine timing information of the hits with a precision of about 3 ns RMS, depending on the signal-to-noise ratio. Both the short shaping time and the hit time finding lead to a significant occupancy reduction and thus ease subsequent track

finding. Thanks to reading several samples the system can tolerate a trigger jitter of up to ± 2 clocks. A dedicated pipelined data processor is implemented for each input, which performs strip reordering, pedestal subtraction, a two-pass common mode correction and zero suppression. It finally encodes position, pulse height and time information of a hit in a single 32 bit word. The acceptable trigger rate is up to 50 kHz, limited by the time needed to read out 6 samples from the APV25.

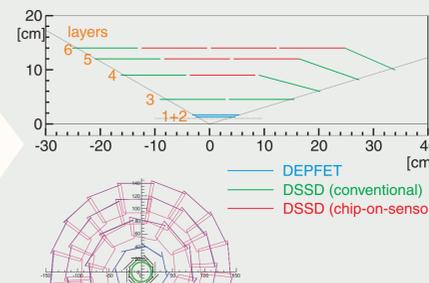
BELLE SVD
Silicon Vertex Detector SVD2.0
Layers: 4
Sensors: 246 (4") double-sided silicon strip detectors (DSSD)
Radii: 2.0...8.8 cm
Active area: 0.5 m²
Readout channels: 111 k
Front-end chip: VA1TA



Upgrade until 2013

Target luminosity: $8 \times 10^{35} \text{ cm}^{-2}\text{s}^{-1}$
About 40 times the present value
Accordingly increase of background
Limits: occupancy, trigger rate (deadtime)

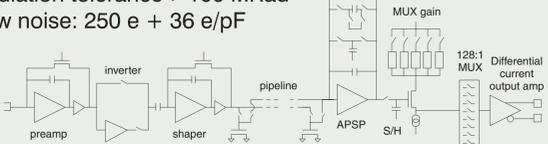
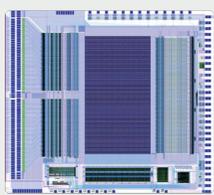
Solution: new vertex detector and readout electronics using APV25



Belle II Silicon Vertex Detector SuperSVD

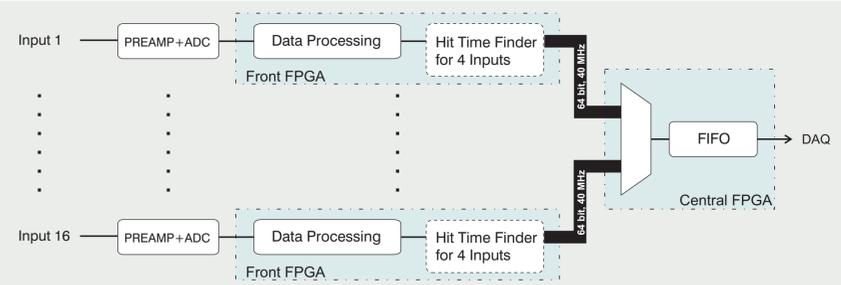
Layers: 2 DEPFET (pixel) + 4 DSSD
Sensors: 182 (6") DSSDs
Radii: 1.8 / 2.2 / 3.8 / 8 / 11.5 / 14 cm
Active area: $\sim 1.2 \text{ m}^2$
Readout channels: 11 Mpx, 240 k strips
Strip readout chip: APV25

APV25 Front-End Chip Features
40 MHz operation
128 channels
192 cell deep analog pipeline
50 ns shaping time (adjustable)
Modes: Peak / Deconvolution / Multi-peak
0.25 μm CMOS process
Radiation tolerance >100 MRad
Low noise: 250 e + 36 e/pF



FADC + PROCESSOR Features

16 input channels
10 bit ADC
Data processing & zero suppression
Hit time reconstruction
64 bit, 40 MHz local bus
Transparent mode (pedestal determination)
Processed mode (optional w/o time finding)



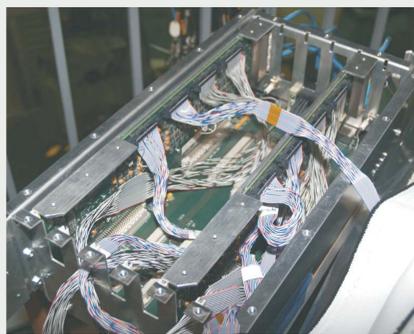
Block diagram of the data processing chain.

The FADC+PROCESSOR is a 9U VME board with 16 input channels used to digitize and process the data of the APV25 chips. The core functions are implemented in FPGAs and thus can easily be adapted by modifying the firmware. A dedicated data processing chain is foreseen for each input, performing APV25 header detection, strip reordering, a two-pass common mode correction, zero suppression and hit time reconstruction (see below). Finally position, pulse height and timing information of a hit are encoded in a single 32 bit wide word. Thanks to the pipelined design with several FIFOs and a 64 bit wide local bus, data can be processed continuously as long as they are fetched by the downstream DAQ system without congestion. Thus the acceptable trigger rate is about 50 kHz, limited by the time needed to read out the samples from the APV25 chips.



Front-end:

Flexible Circuit with thinned APV25 chips using the Chip-on-Sensor concept for low material budget.



Dock-box:

Motherboard (Mambo) with up to 6 Repeater boards (Rebo) for signal level translation, signal buffering, power monitoring and overvoltage protection.

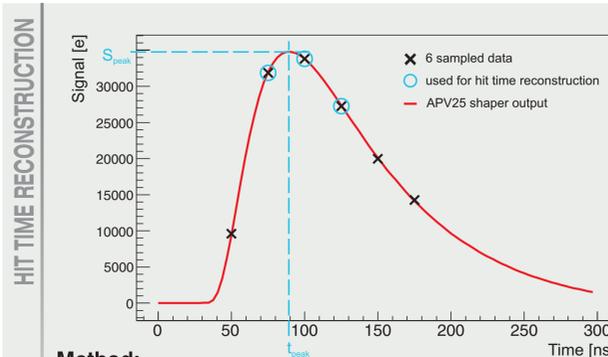


Back-end:

VME controller board (Neco) for trigger and control signals.

FADC boards with online data processing using FPGAs.

Data acquisition

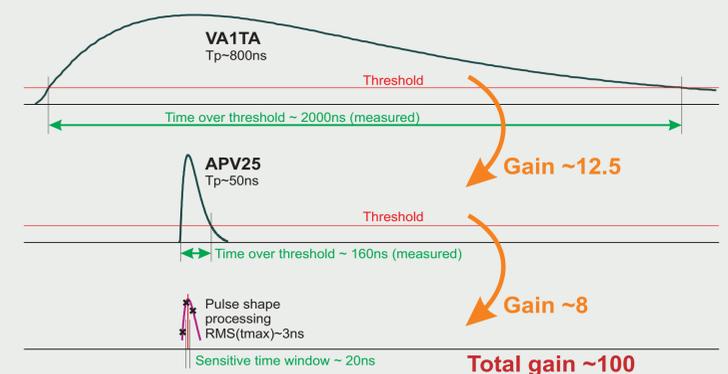


Method:

The multi-peak mode of the APV25 allows to take 3, 6, 9, ... consecutive samples of the shaper output signal. Three points around the maximum of the curve can be used to determine timing and amplitude of the peak with lookup tables, which are generated from the calibration pulse of the APV25. Thanks to using only three out of six samples, a trigger jitter of up to ± 2 clocks can be tolerated. A time resolution of 2 ... 3 ns RMS can be achieved with this method, depending on the signal-to-noise ratio (SNR).

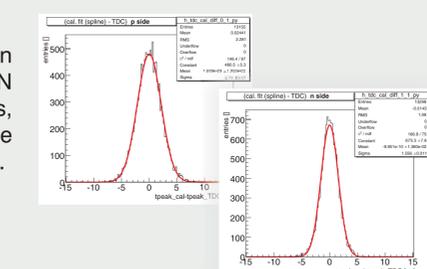
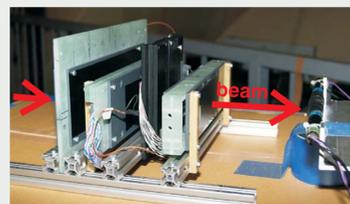
Advantage:

The sensitive time window and thus the occupancy depends on the shaping time (T_p) of the front-end chip. Hence, a gain of ~ 12.5 can be achieved by using the APV25 instead of the VA1TA. However, knowing the timing information of the hits, an additional reduction of the sensitive time window by a factor of ~ 8 is possible. The knowledge of the correct timing further allows to match hits across layers and reject off-time background in the offline analysis.



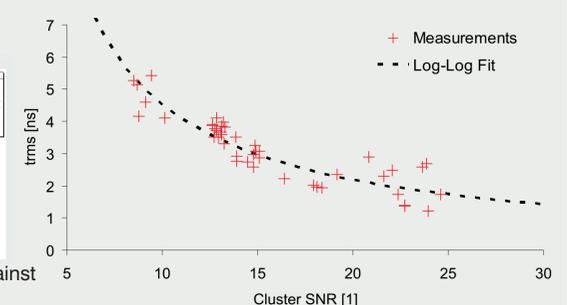
Beam test setup:

The readout system was tested in several beam tests at KEK and CERN together with four DSSD modules, which are all prototypes for the SuperSVD equipped with APV25 chips.



Residual distributions of the fitted peak time against a TDC reference measurement: ~ 2 ns RMS. At the time of the beam test the hit time finder was not yet implemented in the FPGA firmware, a numerical offline fit was used instead.

Time Resolution vs. Cluster SNR



Achieved time resolution of all modules and beam tests as a function of the SNR. The results can be fit by a straight line in a log-log mode.